英特尔[®]与你共创明天[™]

(intel/

IDF2010 英特尔信息技术峰会

Unlocking the Future with Intel

Renée James

Senior Vice President, Intel Corporation General Manager, Software and Services Group



Technology Has Changed the Way We Interact With Our World

2009 1 Atom-based Netbook \$400



Source: Rugged PC Review, Intel



¹⁹⁸¹ 348 IBM PCs **\$1,392,000**

User Expectations Have Changed

Application Seamless Computing Predictability Service Optimized Support Connectivity Network Vailability Just Works! Parallelism Portability Forums **IDF**2010 Secure INTEL DEVELOPER FORUM



Empowering the Future with Intel Architecture Building out the Computing Continuum

Internet Data Center



Application Distribution Channels

Developer Programs and Support

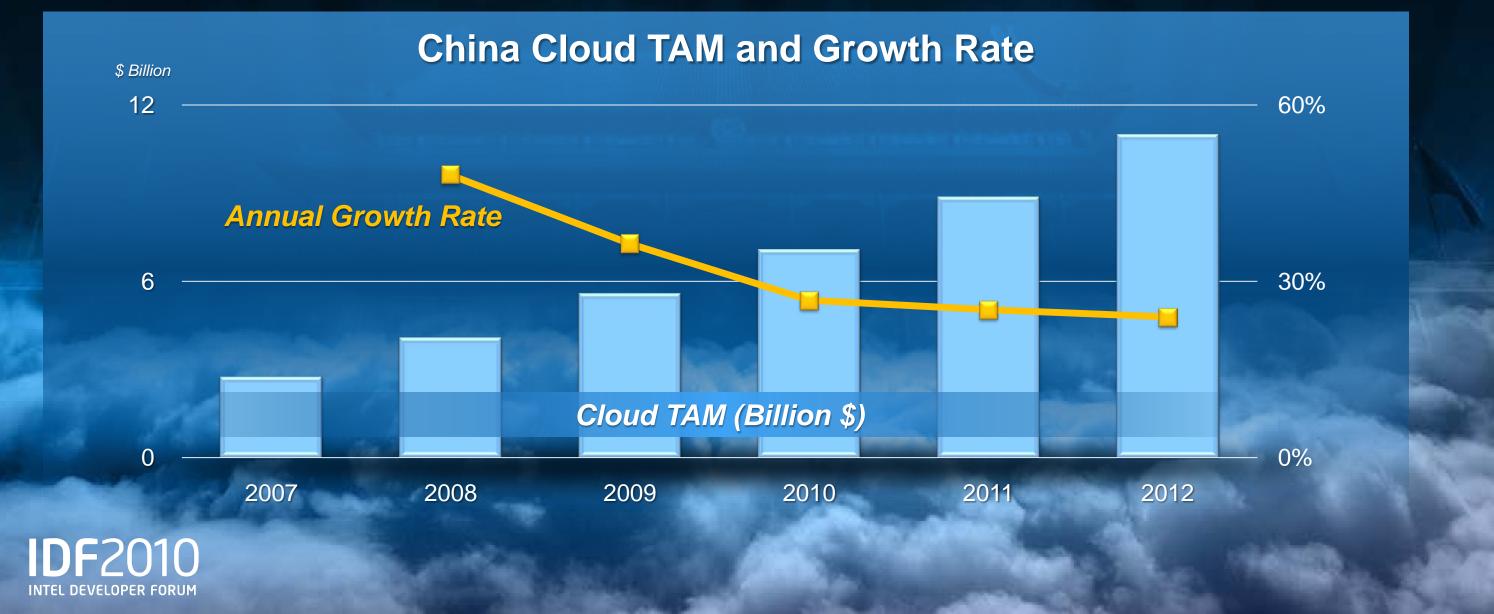
Unified Operating Environment





CE

The Cloud: The First Step in Sharing Information Seamlessly Growing at Double Digits in China



Ellen and Wilson





Intel[®]-Based Systems are Making the Computing Continuum a Reality

Netbook

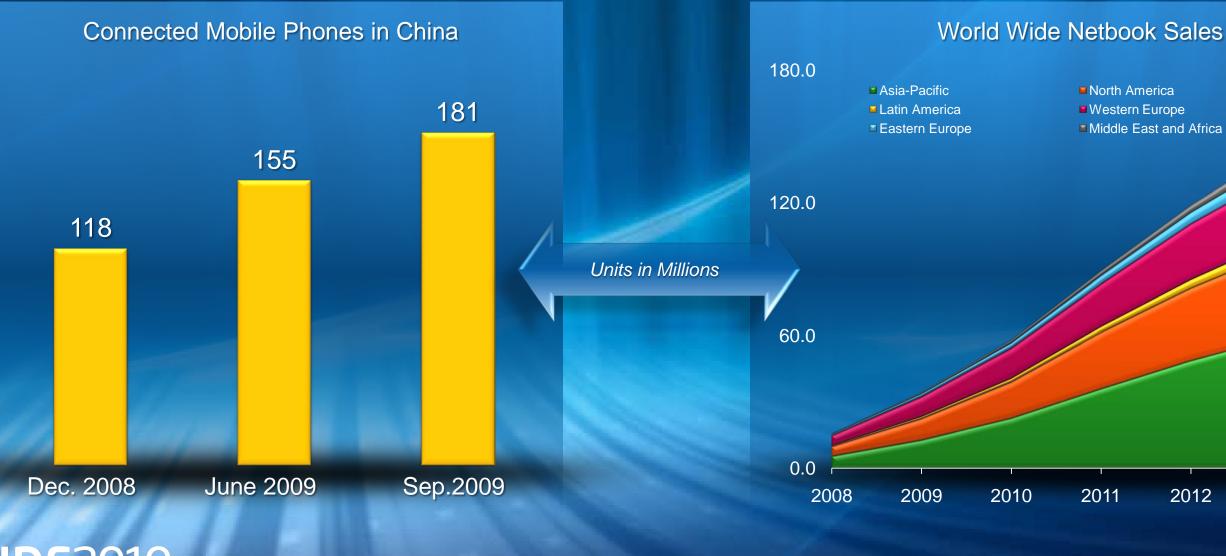
Handheld





CE

The Growth in Handsets and Netbooks **Provide Larger Innovation Paths for Developers**



INTEL DEVELOPER FORUM

Middle East and Africa

2012

2013

2014

Operating Systems for Every Device

an OS

Dahr

1031



Macos



A Single, Unified Operating Environment for Intel[®] Architecture A Broader Foundation for Software Deployment



Unified Operating Environment

The MeeGo[™] Ecosystem







Application Distribution Models Changing How Developers Deliver Their Innovations

Internet Data Center



Application Distribution Channels

Developer Programs and Support

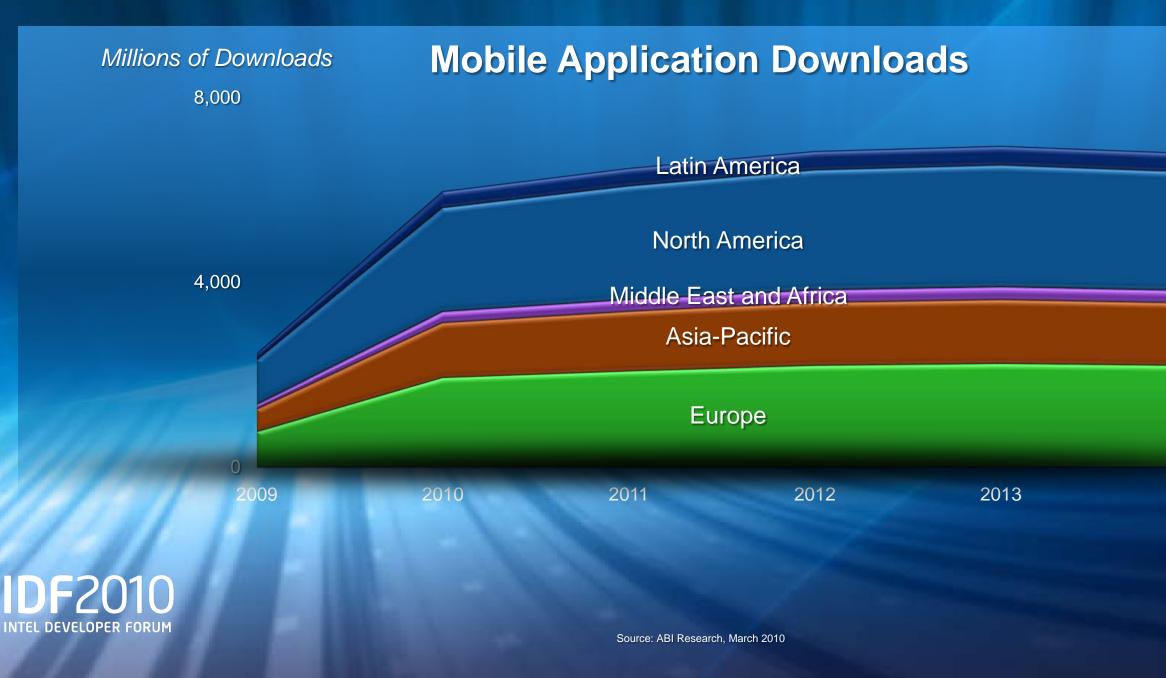
Unified Operating Environment



Embedded

CE

Revenue is Growing in New Channels 23% Annual Growth in Mobile Phone Downloads Alone!





Intel[®] Atom[™] Developer Program and AppUpSM Beta



Application Distribution Channels





AppUpSM Beta is Expanding Announcing...

Chinese Developers Can Ship Applications into AppUpSM Supported Geographies North America and Europe

Application Distribution Channels







Intel[®] is Bringing the Future Closer with Atom[™]-Based Devices



Unified Operating Environment







Building Out China's Clouds

KINGSOFT STDR 盛大网络 weCootton 如何的方件 Evice all Kingdee 2 神州数码 Digital China 次件 ▲ SP 卓望科技 Neusoft东软 WinningSoft

"With the support from Intel... WECOO Cloud can meet the technical requirements of fast response, flexible combination, easy deployment and great scalability."

Chen Shuicao, Dev. Director, UFIDA weCoo Online





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Search

More than Communication

Dr. Jiren Liu Chairman and CEO Neusoft Corporation

Clobal Solutions and Services Offerings

Neusoft, driven by constantly growing competence, provides a wide array of solutions and services offerings for global markets. We have developed a thorough, in-depul; understanding of customers' challenges and accordingly offer tailored, proven solutions. Over 10 years of excellent implementation experience in various verticals, 15,000+ international professionals, on-time & multi-site delivery capability ensure that we

can create competitive advantages for our clients.

IDF2010

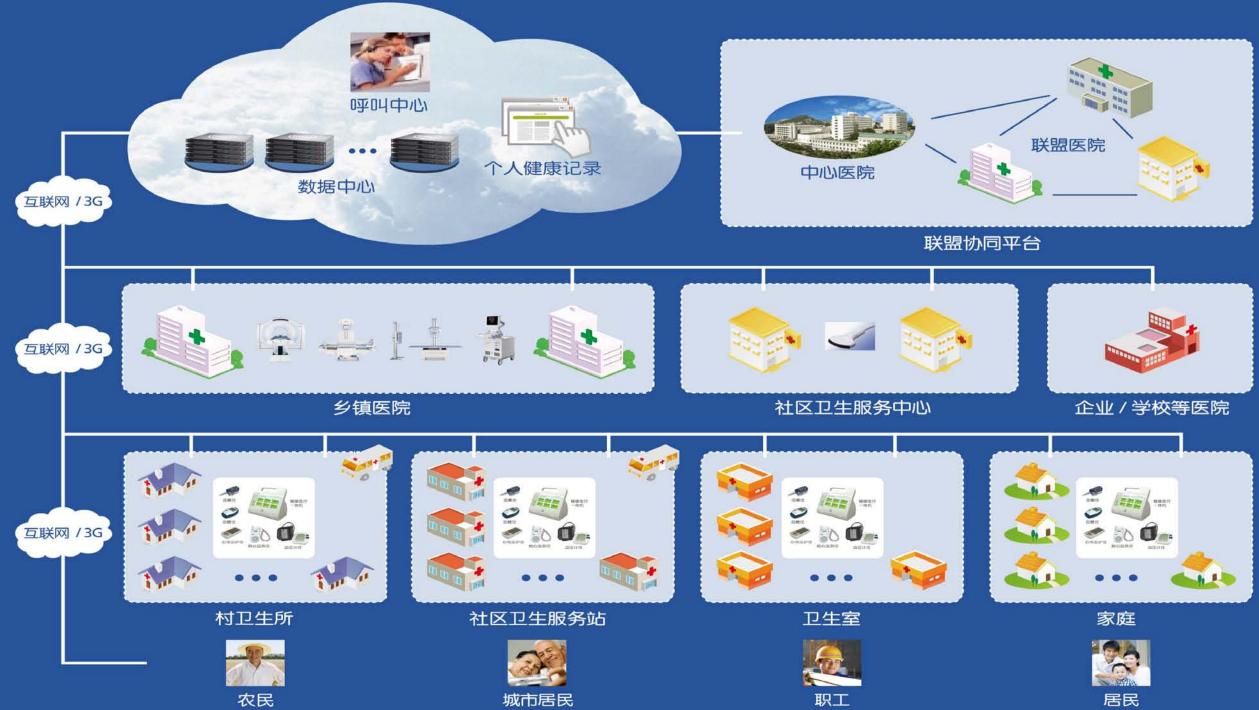
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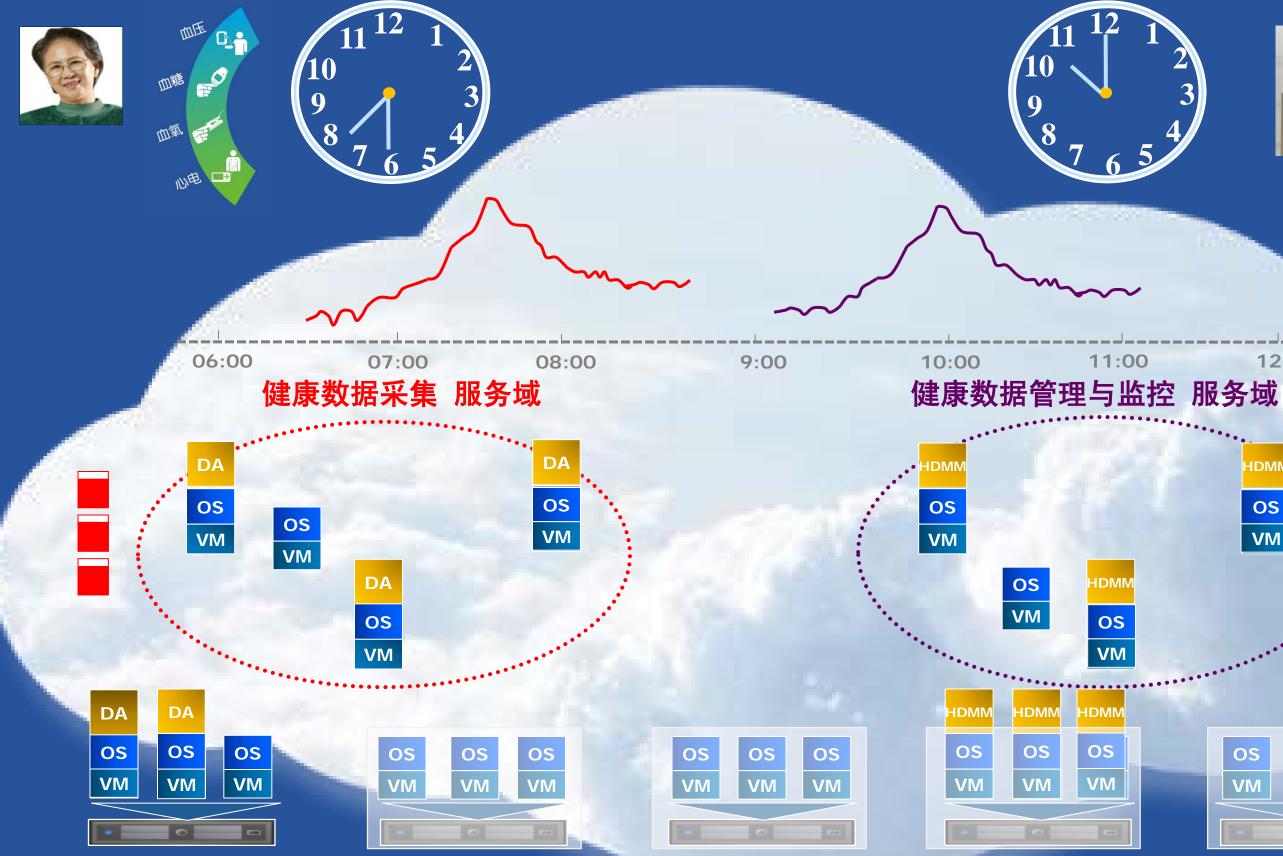
 Neusoft is a leading IT soulies services provider in Chinal allo leading product engineering service provider with worldwide operations, serving a dynamic large corporate sublimited the world Watch this submit to be Neusons

Neuron Man



东软公共健康服务解决方案















Supporting the Growing Resource Requirements in Datacenters Dynamic Power Management on the Server, Rack and Data Center Level

Intel[®] Intelligent Power Node Manager Monitor and Control Server Power

Intel[®] Data Center Manager Manage and Coordinate at the Data Center Level

3

Control individual **SERVER** power consumption

2

Control power used by each RACK



Control power used in each **ROW**



Intel[®] Data Center Manager at Baidu 20% Rack Density Increase!

2

Report system level Policy-based input to control individual Server power consumption

IDF2010

INTEL DEVELOPER FORUM

	_	Server 10		Server 11	
Server 9		Server 9		Server 10	
Server 8		Server 8		Server 9	~
Server 7		Server 7	Rack	Server 8	server/ Rack
Server 6	×	Server 6		Server 7	L.
	n and a second s		server/	Server 6	Ž.
Server 5	er/	Server 5		Server 5	S S
Server 4	eS	Server 4	, si	Server 4	units
Server 3	units server/ Rack	Server 3	10 units	Server 3	Ŧ
Server 2	Ē	Server 2		Server 2	
Server 1	6	Server 1		Server 1	

Control total power dissipation in Group of Servers

> CHILL YOUR CUSTOMERS' POWER DEMANDS The Development Framework for Energy Efficiency

Deployed in Production

Increase rack density from 9 to 11, >20% increase within the same power budget and SLA

Manage and Coordinate at the server and Data Center Level



Intel[®] Core[™] Laptops and Desktop Capabilities are Increasing

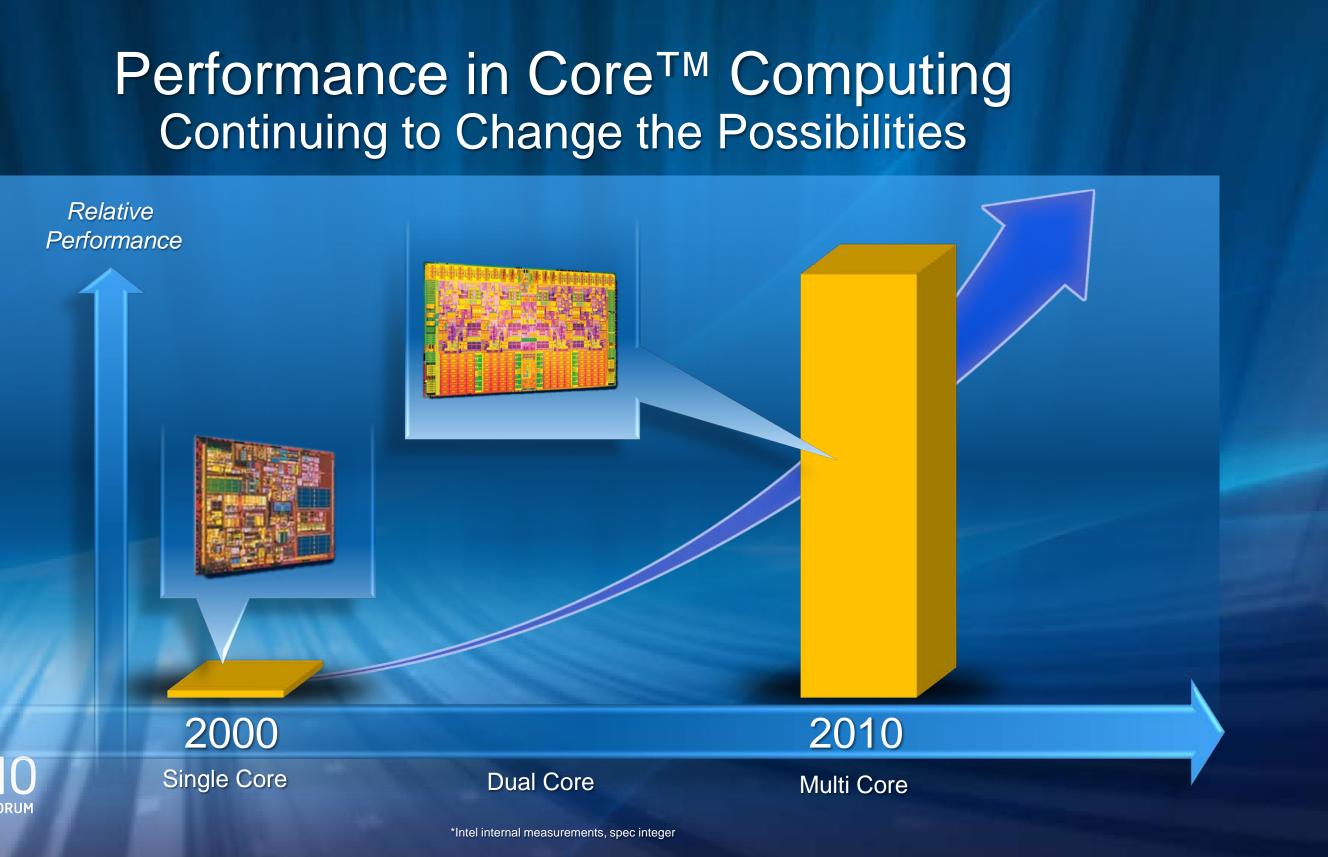
Laptop

Desktop





Continuing to Change the Possibilities



INTEL DEVELOPER FORUM

Intel[®] Tools Bring Code to Life Faster









Source: Tencent performance measurement







1.1

Intel[®] is Empowering Developers to Create the Future of Computing

Internet Data Center



Application Distribution Channels

Developer Programs and Support

Unified Operating Environment





Visit the Software Booth for More Ideas









3Dijov





Tencent 腾讯

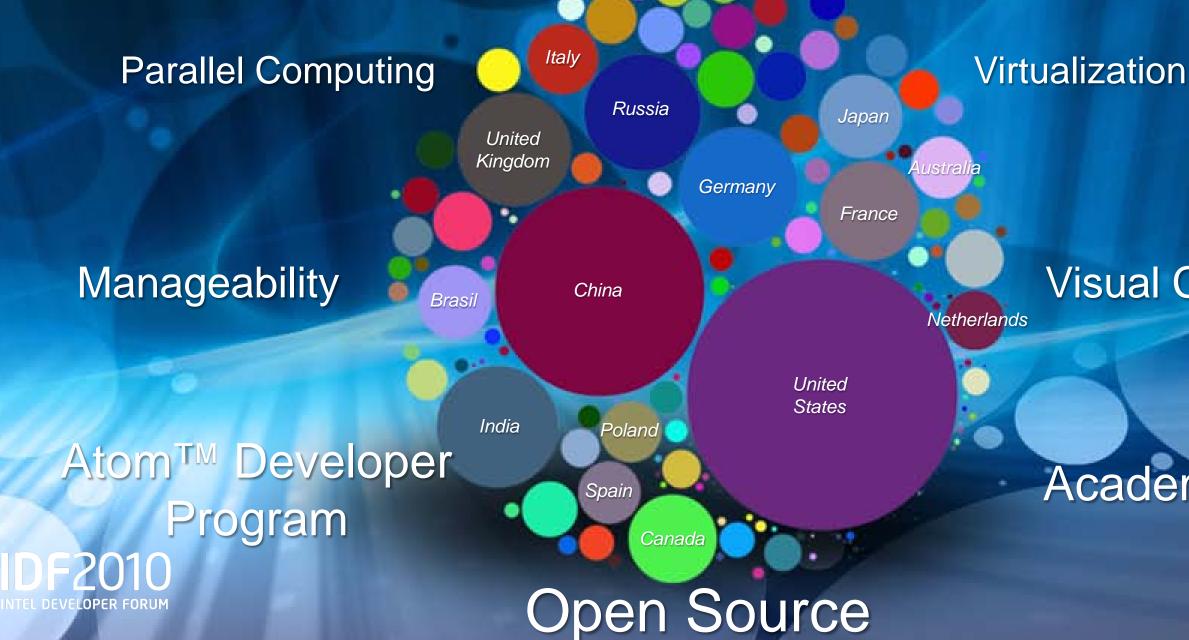




StarSoftComm 软通科技



Millions of Developers Utilize the Array of Resources Available for Intel® Architecture



Visual Computing

Academic

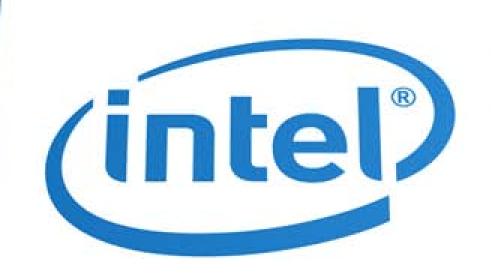








Helping You Make the Future a Reality!



Software

KILOWATT:



Intel China Software Center



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(intel/



Intel estimates based on:

Intel internal measurements

http://www.spec.org/osg/cpu2000/results/res2000q1/cpu2000-20000314-00051.html http://www.spec.org/osg/cpu2000/results/res2005q4/cpu2000-20051208-05160.html http://www.spec.org/osg/cpu2000/results/res2006q4/cpu2000-20061113-08053.html http://www.spec.org/cpu2006/results/res2007q4/cpu2006-20071112-02555.html http://www.spec.org/cpu2006/results/res2008q4/cpu2006-20081024-05712.html http://www.spec.org/cpu2006/results/res2010q1/cpu2006-20100315-10007.html



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Rev. 1/14/10

